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## (54) LED-CHIP SORTING DEVICE AND LED CHIP MANUFACTURING METHOD

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(57)**ABSTRACT** 

A light-emitting diode (LED)-chip sorting device includes a wafer stage configured to load a wafer including a plurality of LED chips thereon, a film stage configured to load a film thereon, a pick-up unit configured to arrange, on the film loaded on the film stage, the plurality of LED chips loaded on the wafer stage, and a controller configured to control the pick-up unit to sequentially pick up the plurality of LED chips from the wafer stage in a preset pick-up direction. The preset pick-up direction is one of a first pick-up direction defined from a center portion of the wafer toward an edge of the wafer, and a second pick-up direction defined from the edge of the wafer toward the center portion of the wafer.

